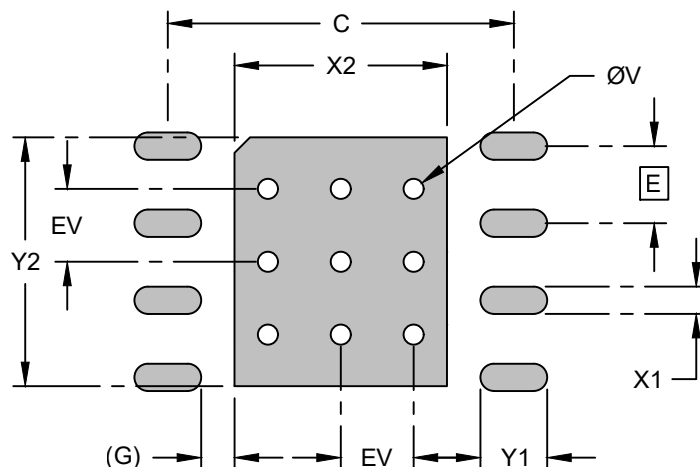


# 8-Lead Plastic Very, Very Thin Small Outline No-Lead (MF) - 6x5x0.8 mm Body [WSON] (Also Called WDFN)

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



## RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Optional Center Pad Width	X2			3.50
Optional Center Pad Length	Y2			4.10
Contact Pad Spacing	C	5.70		
Contact Pad Width (X20)	X1			0.45
Contact Pad Length (X20)	Y1			1.10
Contact Pad to Center Pad (X20)	(G)	0.55 (REF)		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

### Notes:

- Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
- For best soldering results, please refer to the current industry standard IPC-7093.